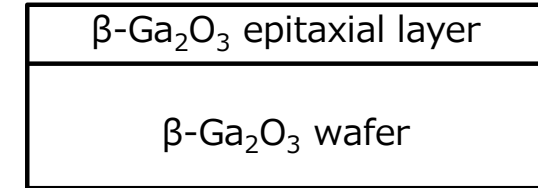


# Standard specifications of 100 mm $\beta$ -Ga<sub>2</sub>O<sub>3</sub> epitaxial wafer (by HVPE)

## Epitaxial layer

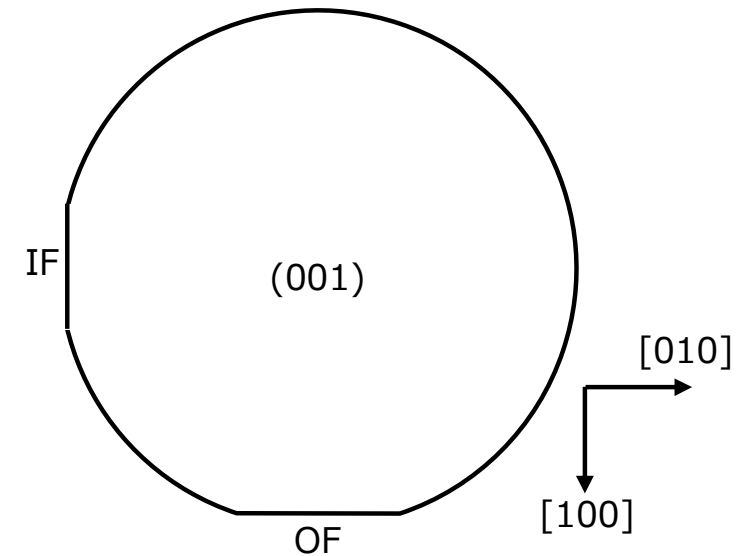
Items	Specifications
Dopant	Si (n-type)
Doping concentration <small>*A value can be selected in increments of <math>1 \times 10^{16} \text{ cm}^{-3}</math>.</small>	Specify a value in the range between $1 \times 10^{16}$ and $9 \times 10^{16} \text{ cm}^{-3}$
Thickness <small>*A value can be selected in increments 1 <math>\mu\text{m}</math>.</small>	Specify a value in the range between 5 and 10 $\mu\text{m}$



Cross section of  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> epitaxial wafer

## Epi-Wafer

Items	Specifications
Substrate dopant	Sn (n-type)
Substrate resistivity	0.007–0.042 $\Omega \cdot \text{cm}$
Surface orientation	(001)
Backside finish	Grinding
Wafer thickness	620 $\mu\text{m}$
XRD FWHM <small>*Not included in a delivery inspection sheet</small>	$\leq 50 \text{ arcsec}$



Orientation



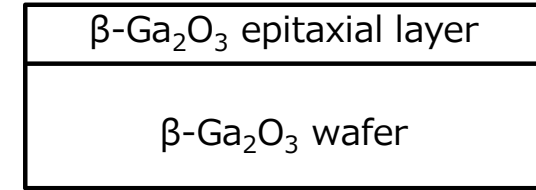
### Remarks

- 1 There are cases in which the other side of OF is chipped (a maximum of around IF width).
- 2 These products must be used for research and development purposes only.
- 3 The substrates must not be used as a seed crystal.
- 4 The specifications are subject to change without notice.

# Standard specifications of 2 inch $\beta$ -Ga<sub>2</sub>O<sub>3</sub> epitaxial wafer (by HVPE)

## Epitaxial layer

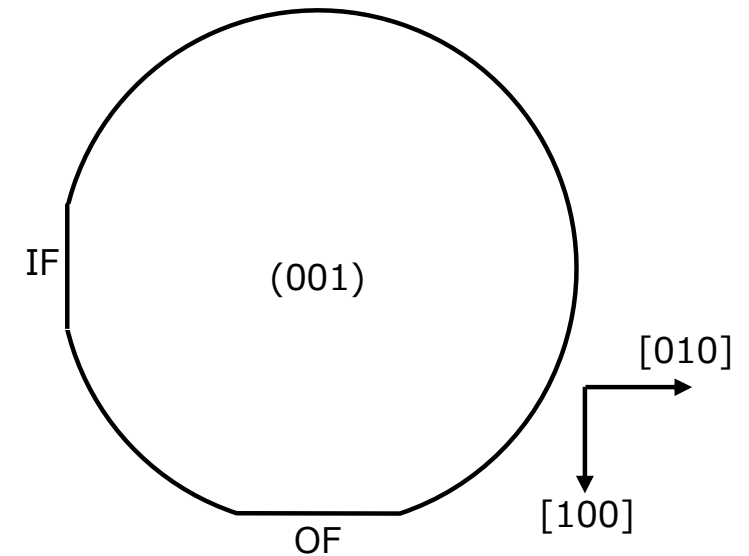
Items	Specifications
Dopant	Si (n-type)
Doping concentration <small>*A value can be selected in increments of <math>1 \times 10^{16} \text{ cm}^{-3}</math>.</small>	Specify a value in the range between $1 \times 10^{16}$ and $9 \times 10^{16} \text{ cm}^{-3}$
Thickness <small>*A value can be selected in increments 1 <math>\mu\text{m}</math>.</small>	Specify a value in the range between 5 and 10 $\mu\text{m}$



Cross section of  $\beta$ -Ga<sub>2</sub>O<sub>3</sub> epitaxial wafer

## Epi-Wafer

Items	Specifications
Substrate dopant	Sn (n-type)
Substrate resistivity	0.007–0.042 $\Omega \cdot \text{cm}$
Surface orientation	(001)
Backside finish	Grinding
Wafer thickness	640 $\mu\text{m}$
XRD FWHM <small>*Not included in a delivery inspection sheet</small>	$\leq 50 \text{ arcsec}$



Orientation



### Remarks

- 1 There are cases in which the other side of OF is chipped (a maximum of around IF width).
- 2 These products must be used for research and development purposes only.
- 3 The substrates must not be used as a seed crystal.
- 4 The specifications are subject to change without notice.